MEMS CLEAN ROOM

- 1500 m², class 10
- 150 mm (6”) Wafer line
- 3 shift preparation for R&D and pilot fabrication (24x5)
- Access to external services
- Technological parameter supervising system
- MES / PPS based planning and documentation
- ISO 9001 certification
MEMS Clean Room Layout
Aktuelle Clusterung

CHARACTERIZATION & TEST
BACK END
WET ETCH / CLEANING
INLINE METROLOGY
SEM
LAB
CVD
HIGH TEMPERATURE
CMP

BACK END
LOGISTICS
EXTERNAL PARTNERS
LITHOGRAPHY
DRY ETCH / PVD

GOWNING AREA

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MEMS Clean Room: Characterization & Test
MEMS Clean Room: Lithography
MEMS Clean Room: Wet Etch / Cleaning
MEMS Clean Room: Wet Etch / Cleaning
MEMS Clean Room: Dry Etch / Strip Resist
MEMS Clean Room: Backend (Bonding, Dispense)
MEMS Clean Room: Inline Metrology
MEMS Clean Room: Inline Metrology
MEMS Clean Room: SEM